

ADHESIVE FILM AND SEMICONDUCTOR PACKAGE USING ADHESIVE FILM

Abstract

An adhesive film that can solve the problem of pickup defect and improve the yield rate of semiconductor packages is provided.

Specifically, it is an adhesive film, which comprises: (A) a bismaleimide resin; (B) a radical initiator; and (C) a coupling agent that contains a (meth)acrylic group.

Further, an adhesive film with dicing tape, which comprises such an adhesive film laminated onto a dicing tape, is provided.

Furthermore, a semiconductor package that comprises such an adhesive film with dicing tape is provided.

[Figure.1]